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PATENT

*Heilly*  
6/16/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application: Morrison et al.

Group Art Unit: 1713

Serial No.: 09/439,655

Examiner: M. Reddick

Filed: November 12, 1999

Atty. Docket No.: 1843

140  
*u*

For: LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE

AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This is in response to the Office action, paper No. 12, mailed February 12, 2003, for which a response is due June 12, 2003 by virtue of the concurrently filed request for a one (1) month extension of time. A Notice of Appeal is concurrently filed herewith.

Please amend the application as follows:

In the Claims

Cancel claims 10 and 12 in their entireties without prejudice.

Amend claims 1, 8 and 11 to read as follows:

Claim 1. A hot melt adhesive composition comprising, by weight of the hot melt adhesive composition,

a) about 5 weight percent to about 60 weight percent of an ethylene-vinyl acetate copolymer having a vinyl acetate content of about 30 weight percent to 50 weight percent and a melt index of about 700 to 4,000 dg/min;

*Do not Enter  
06/27/03  
Dmr*